2SC3931

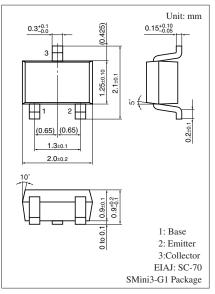
Silicon NPN epitaxial planar type

For high-frequency amplification

Features

- Optimum for RF amplification of FM/AM radios
- \bullet High transition frequency $f_{\rm T}$
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

Absolute Maximum Ratings $T_a = 25^{\circ}C$ Parameter Symbol Unit Rating Collector-base voltage (Emitter open) 30 V V_{CBO} Collector-emitter voltage (Base open) V_{CEO} 20 V 3 V Emitter-base voltage (Collector open) V_{EBO} 15 Collector current I_C mА Collector power dissipation 150 mW $\mathbf{P}_{\mathbf{C}}$ T_j 150 °C Junction temperature °C Storage temperature T_{stg} -55 to +150



Marking Symbol: U

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

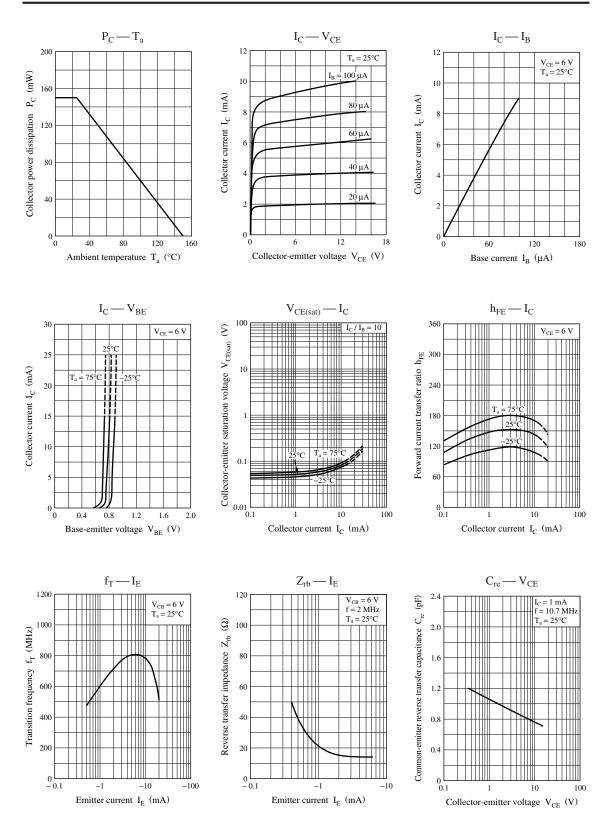
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{C} = 10 \ \mu A, \ I_{E} = 0$	30			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_E = 10 \ \mu A, \ I_C = 0$	3			V
Base-emitter voltage	V _{BE}	$V_{CB} = 6 V, I_E = -1 mA$		720		mV
Forward current transfer ratio *	h _{FE}	$V_{CB} = 6 V, I_E = -1 mA$	65		260	
Transition frequency	f _T	$V_{CB} = 6 V, I_E = -1 mA, f = 200 MHz$	450	650		MHz
Common-emitter reverse transfer capacitance	C _{re}	$V_{CB} = 6 V, I_E = -1 mA, f = 10.7 MHz$		0.8	1.0	pF
Power gain	G _P	$V_{CB} = 6 V, I_E = -1 mA, f = 100 MHz$		24		dB
Noise figure	NF	$V_{CB} = 6 V, I_E = -1 mA, f = 100 MHz$		3.3		dB

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

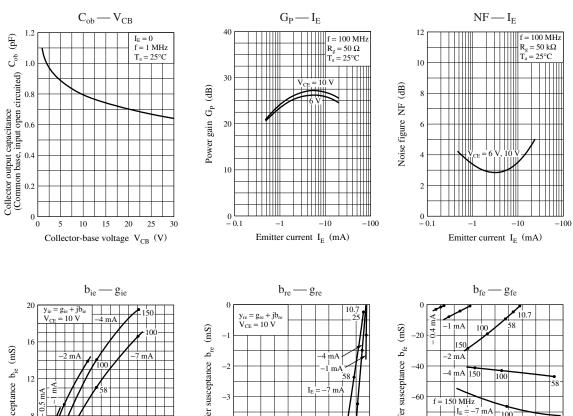
2. *: Rank classification

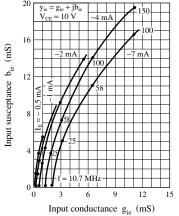
Rank	С	D
$h_{\rm FE}$	65 to 160	100 to 260

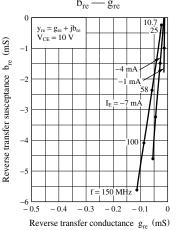
Panasonic

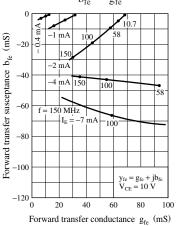


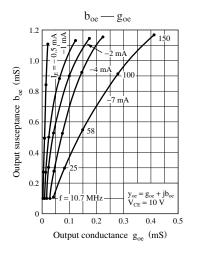
Panasonic











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